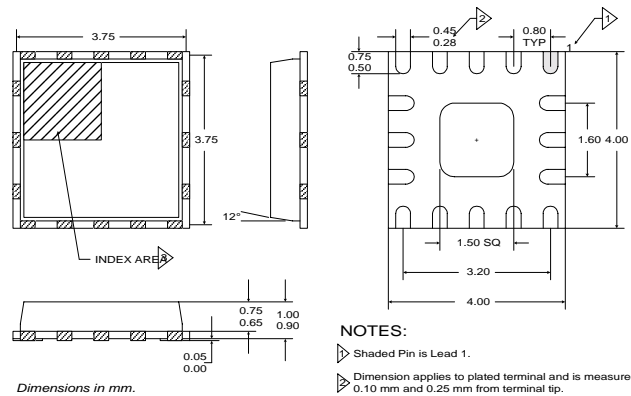


Typical Applications

- 3V CDMA/AMPS Cellular Handsets
- 3V JCDMA Cellular Handsets
- 3V CDMA2000 Cellular Handsets
- 3V TDMA/GAIT Cellular Handsets
- Spread-Spectrum Systems
- Portable Battery-Powered Equipment

Product Description

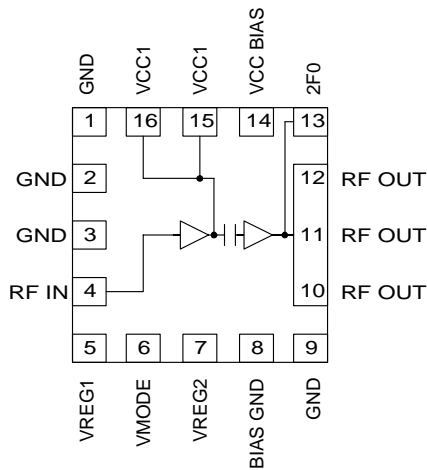
The RF2192 is a high-power, high-efficiency linear amplifier IC targeting 3V handheld systems. The device is manufactured on an advanced Gallium Arsenide Heterojunction Bipolar Transistor (HBT) process, and has been designed for use as the final RF amplifier in dual-mode 3V CDMA/AMPS and CDMA2000 handheld digital cellular equipment, spread-spectrum systems, and other applications in the 800MHz to 960MHz band. The RF2192 has a low power mode to extend battery life under low output power conditions. The device is packaged in a 16 pin, 4mmx4mm leadless chip carrier.



- NOTES:
- ▷ Shaded Pin is Lead 1.
  - ▷ Dimension applies to plated terminal and is measured 0.10 mm and 0.25 mm from terminal tip.
  - ▷ The terminal #1 identifier and terminal numbering convention shall conform to JESD 95-1 SPP-012. Details of terminal identifier are optional, but must be located within the z indicated. The identifier may be either a mold or mark feature.
  - 4 Pins 1 and 9 are fused.
  - 5 Package Warpage: 0.05 max.

Optimum Technology Matching® Applied

- Si BJT       GaAs HBT       GaAs MESFET  
 Si Bi-CMOS       SiGe HBT       Si CMOS



Functional Block Diagram

Package Style: LCC, 16-Pin, 4 x 4

Features

- Single 3V Supply
- 29dBm Linear Output Power
- 37% Linear Efficiency
- Low Power Mode
- 45 mA idle current
- 47% Peak Efficiency 31 dBm Output

Ordering Information

- RF2192      3V 900MHz Linear Power Amplifier  
 RF2192 PCBA      Fully Assembled Evaluation Board

RF Micro Devices, Inc.  
7628 Thorndike Road  
Greensboro, NC 27409, USA

Tel (336) 664 1233  
Fax (336) 664 0454  
<http://www.rfmd.com>

### Absolute Maximum Ratings

Parameter	Rating	Unit
Supply Voltage (RF off)	+8.0	V <sub>DC</sub>
Supply Voltage (P <sub>OUT</sub> ≤31dBm)	+5.2	V <sub>DC</sub>
Mode Voltage (V <sub>MODE</sub> )	+4.2	V <sub>DC</sub>
Control Voltage (V <sub>REG</sub> )	+3.0	V <sub>DC</sub>
Input RF Power	+10	dBm
Operating Case Temperature	-30 to +110	°C
Storage Temperature	-30 to +150	°C
Moisture Sensitivity	Modified JEDEC Level 2	



**Caution!** ESD sensitive device.

RF Micro Devices believes the furnished information is correct and accurate at the time of this printing. However, RF Micro Devices reserves the right to make changes to its products without notice. RF Micro Devices does not assume responsibility for the use of the described product(s).

Parameter	Specification			Unit	Condition
	Min.	Typ.	Max.		
<b>High Power State</b> <b>(V<sub>MODE</sub> Low)</b>					Case T=25°C, V <sub>CC</sub> =3.4V, V <sub>REG</sub> = 2.85V, V <sub>MODE</sub> =0V to 0.5V, Freq=824MHz to 849MHz (unless otherwise specified)
Frequency Range	824		849	MHz	
Linear Gain	27	30		dB	
Second Harmonic		-33		dBc	
Third Harmonic		<-60		dBc	
Maximum Linear Output Power (CDMA Modulation)	29			dBm	
Total Linear Efficiency		37		%	P <sub>OUT</sub> =29dBm
Adjacent Channel Power Rejection		-48	-44	dBc	ACPR @ 885kHz
		-58	-56	dBc	ACPR @ 1980kHz
Input VSWR		2:1			
Output VSWR			10:1		No damage.
			6:1		No oscillations. > -70dBc
Noise Power		-133		dBm/Hz	At 45MHz offset
<b>Low Power State</b> <b>(V<sub>MODE</sub> High)</b>					Case T=25°C, V <sub>CC</sub> =3.4V, V <sub>REG</sub> =2.85V, V <sub>MODE</sub> =1.8V to 3V, Freq=824MHz to 849MHz (unless otherwise specified)
Frequency Range	824		849	MHz	
Linear Gain	19	22		dB	
Second Harmonic		-33		dBc	
Third Harmonic		<-60		dBc	
Maximum Linear Output Power (CDMA Modulation)	16	20		dBm	
Max I <sub>CC</sub>		150		mA	P <sub>OUT</sub> =+16dBm (all currents included)
Adjacent Channel Power Rejection		-48	-46	dBc	ACPR @ 885kHz
		<-60	-58	dBc	ACPR @ 1980kHz
Input VSWR		2:1			
Output VSWR			10:1		No damage.
			6:1		No oscillations. > -70dBc

Parameter	Specification			Unit	Condition
	Min.	Typ.	Max.		
<b>High Power State CDMA 2000 1x (V<sub>MODE</sub> LOW)</b>					
Frequency Range	824		849	MHz	Case T=25°C, V <sub>CC</sub> =3.4V, V <sub>REG</sub> =2.85V. V <sub>MODE</sub> =0V to 0.5V, Freq=824MHz to 849MHz (unless otherwise specified)
Linear Gain		29		dB	
Pilot+DCCH 9600					
Maximum Linear Output Power (CDMA 2000 Modulation)	26.5			dBm	
Adjacent Channel Power Rejection		-47		dBc	
		<-60		dBc	
Pilot+FCH 9600+SCHO 9600					
Maximum Linear Output Power (CDMA 2000 Modulation)	29			dBm	
Adjacent Channel Power Rejection		-47		dBc	
		<-60		dBc	
<b>Low Power State CDMA 2000 1x (V<sub>MODE</sub> HIGH)</b>					
Frequency Range	824		849	MHz	Case T=25°C, V <sub>CC</sub> =3.4V, V <sub>REG</sub> =2.85V. V <sub>MODE</sub> =1.8V to 3V, Freq=824MHz to 849MHz
Linear Gain		22		dB	
Pilot+DCCH 9600					
Maximum Linear Output Power (CDMA 2000 Modulation)	16	20		dBm	
Adjacent Channel Power Rejection		-48		dBc	
		<-85		dBc	
Efficiency		15		%	
Pilot+FCH 9600+SCHO 9600					
Maximum Linear Output Power (CDMA 2000 Modulation)	16	20		dBm	
Adjacent Channel Power Rejection		<-50		dBc	
		<-65		dBc	
<b>FM Mode</b>					
Frequency Range	824		849	MHz	Case T=25°C, V <sub>CC</sub> =3.4V, V <sub>REG</sub> =2.85V, V <sub>MODE</sub> =0V to 0.5V, Freq=824MHz to 849MHz (unless otherwise specified)
Gain		30		dB	
Second Harmonic		-33		dBc	
Third Harmonic		<-60		dBc	
Max CW Output Power	31	32		dBm	
Total Efficiency (AMPS mode)		47		%	
Input VSWR		2:1			
Output VSWR			10:1		
			6:1		

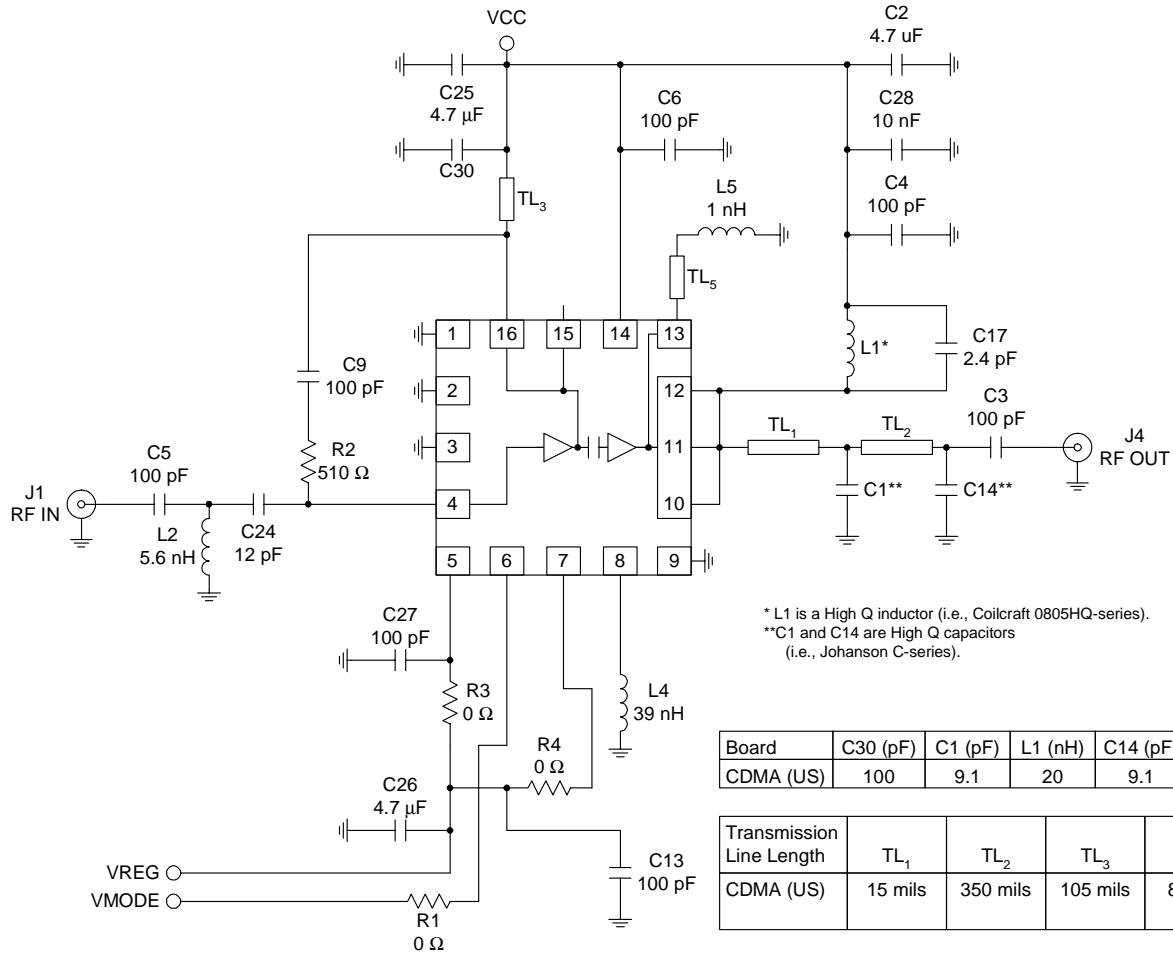
Note: DCCH: Dedicated Control Channel  
 FCH: Fundamental Channel  
 CCDF: Complementary Cumulative Distribution Function

Parameter	Specification			Unit	Condition
	Min.	Typ.	Max.		
<b>DC Supply</b>					
Supply Voltage	3.0	3.4	4.2	V	The maximum power out for $V_{CC}=3.0V$ is 28dBm. $V_{MODE}=Low$ $V_{MODE}=High$
Quiescent Current		160		mA	
$V_{REG}$ Current		45	70	mA	
$V_{MODE}$ Current			10	mA	
Turn On/Off Time			1	mA	
			<40	$\mu s$	Time between $V_{REG}$ turned on and PA reaching full power. Turn on/off time can be reduced by lowering the bypass capacitor value on the $V_{REG}$ line.
Total Current (Power Down)			10	$\mu A$	$V_{REG}=Low$
$V_{REG}$ "Low" Voltage	0		0.5	V	
$V_{REG}$ "High" Voltage	2.75	2.85	2.95	V	
$V_{MODE}$ "Low" Voltage	0		0.5	V	
$V_{MODE}$ "High" Voltage	1.8	2.85	3.0	V	

Pin	Function	Description	Interface Schematic
1	GND	Ground connection.	
2	GND	Ground connection.	
3	GND	Ground connection.	
4	RF IN	RF input. An external 100pF series capacitor is required as a DC block. In addition, shunt inductor and series capacitor are required to provide 2:1 VSWR.	
5	VREG1	Power Down control for first stage. Regulated voltage supply for amplifier bias. In Power Down mode, both $V_{REG}$ and $V_{MODE}$ need to be LOW (<0.5V).	
6	VMODE	For nominal operation (High Power Mode), $V_{MODE}$ is set LOW. When set HIGH, the driver and final stage are dynamically scaled to reduce the device size and as a result to reduce the idle current.	
7	VREG2	Power Down control for the second stage. Regulated voltage supply for amplifier bias. In Power Down mode, both $V_{REG}$ and $V_{MODE}$ need to be LOW (<0.5V).	
8	BIAS GND	Bias circuitry ground. See application schematic.	
9	GND	Ground connection.	
10	RF OUT	RF output and power supply for final stage. This is the unmatched collector output of the second stage. A DC block is required following the matching components. The biasing may be provided via a parallel L-C set for resonance at the operating frequency of 824MHz to 849MHz. It is important to select an inductor with very low DC resistance with a 1A current rating. Alternatively, shunt microstrip techniques are also applicable and provide very low DC resistance. Low frequency bypassing is required for stability.	
11	RF OUT	Same as pin 10.	See pin 10.
12	RF OUT	Same as pin 10.	
13	2FO	Harmonic trap. This pin connects to the RF output but is used for providing a low impedance to the second harmonic of the operating frequency. An inductor or transmission line resonating with an on chip capacitor at 2fo is required at this pin.	
14	VCC BIAS	Power supply for bias circuitry. A 100pF high frequency bypass capacitor is recommended.	
15	VCC1	Power supply for first stage.	
16	VCC1	Same as Pin 15.	
Pkg Base	GND	Ground connection. The backside of the package should be soldered to a top side ground pad which is connected to the ground plane with multiple vias. The pad should have a short thermal path to the ground plane.	

## Evaluation Board Schematic US - CDMA

(Download [Bill of Materials](http://www.rfmd.com) from [www.rfmd.com](http://www.rfmd.com).)



### Evaluation Board Layout 2.0" x 2.0"

Board Thickness 0.031", Board Material FR-4, Multi-Layer, Ground Plane at 0.015"

